ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES*	Material Composit © Copyright 2005. IPC, international and Pan-Art	Bannockb	urn, Illinois. A	ll rights reserved u ntions.	nder both	This docum level parts,	ent is a declara he declaration	ion of the sencompasse	ubstances es all lower	within the manufactu r level materials for w	rer listed i hich the n	tem. Note: if nanufacturer	the item is an as has engineering	ssembly with lower responsibility.	
1752-21.1					Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				als and Mfg Information					
Supplier Informa	tion														
Company name*			Company unique ID			Unique ID Authority				Response Date*					
onsemi												2025-05-13			
Contact Name			Title - Contact				Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative				Phone - Representative*				Email - Representative*				
Product-Env-Steward	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
Requester I	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date	Date Version Manufacturing Site		Manufacturing Site		Weight*	UOM	Unit Type	
		FDMS86	DMS86102LZ FET 100V		25.0 mOhm PQFN56		2025-05-13		C	СŊЈ		105.957	mg	Each	
Manufacturing P	roccess Information	1													
Terminal Plating / Grid Array Material Terr			erminal Base Alloy J-STD-020 MSL			L Rating	Peak Process Body Temperature Max Time at Pea			k Temperature Number of Reflow Cycles					
Matte Tin (Sn) - annealed CU			U Alloy	Alloy 1			260 C 30			seconds 3					
Comments															
evel 1 - maximum tim	e at peak temperature d	luring sol	dering is 10-3	0 seconds											
for more information	regarding material com	position p	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).									
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature	astislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	5.09	mg	Supplier	Silicon (Si)	7440-21-3		5.09	mg
Die Attach Solder	6.941	mg	Supplier	Silver (Ag)	7440-22-4		0.1735	mg
			А	Lead (Pb)	7439-92-1	7a	6.4204	mg
			Supplier	Tin (Sn)	7440-31-5		0.3471	mg
Lead Frame	35.434	mg	Supplier	Silver (Ag)	7440-22-4		0.038	mg
			Supplier	Zinc (Zn)	7440-66-6		0.046	mg
			Supplier	Iron (Fe)	7439-89-6		0.85	mg
			Supplier	Copper (Cu)	7440-50-8		34.5	mg
Mold Compound-Black	44.401	mg		Epoxy resin	proprietary data		5.9053	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0888	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		38.4069	mg
lating	13.5	mg	Supplier	Tin (Sn)	7440-31-5		13.5	mg
Wire Bond - Cu	0.591	mg	Supplier	Copper (Cu)	7440-50-8		0.591	mg